

1 **DECLARATION OF SOLE INVENTOR FOR PATENT APPLICATION**

2 As the below named inventor, I hereby declare that:

3 My residence, post office address and citizenship are as stated
4 below next to my name.

5 I believe I am the original, first and sole inventor of the subject
6 matter which is claimed and for which a patent is sought on the
7 invention entitled: **Semiconductor Processing Methods of Forming A**
8 **Conductive Gate and Line**, the specification of which is attached hereto.

9 I hereby state that I have reviewed and understand the contents
10 of the above-identified specification, including the claims.

11 I acknowledge the duty to disclose information known to me to
12 be material to patentability as defined in Title 37, Code of Federal
13 Regulations §1.56.

14
15 **PRIOR FOREIGN APPLICATIONS:**

16 I hereby state that no applications for foreign patents or inventor's
17 certificates have been filed prior to the date of execution of this
18 declaration.

19
20 **POWER OF ATTORNEY:**

21 As a named Inventor, I hereby appoint the following attorneys and
22 agent to prosecute this application and transact all business in the
23 Patent and Trademark Office connected therewith: Richard J. St. John,
24 Reg. No. 19,363; David P. Roberts, Reg. No. 23,032; Randy A. Gregory,

86E140-44965060

1 Reg. No. 30,386; Mark S. Matkin, Reg. No. 32,268; James L. Price, Reg.
2 No. 27,376; Deepak Malhotra, Reg. No. 33,560; Mark W. Hendricksen,
3 Reg. No. 32,356; David G. Latwesen, Reg. No. 38,533; George G.
4 Grigel, Reg. No. 31,166; Keith D. Grzelak, Reg. No. 37,144; John S.
5 Reid, Reg. No. 36,369; Lance R. Sadler, Reg. No. 38,605; James D.
6 Shaurette, Reg. No. 39,833; W. Bryan Farney, Reg. No. 32,651; Lia M.
7 Pappas, Reg. No. 34,095; and Michael L. Lynch, Reg. No. 30,871.

8 Send correspondence to: WELLS, ST. JOHN, ROBERTS,
9 GREGORY & MATKIN P.S., 601 W. First Avenue, Suite 1300, Spokane,
10 WA 99204-0317. Direct telephone calls to: Lance R. Sadler
11 (509) 624-4276.

12 I hereby declare that all statements made herein of my own
13 knowledge are true and that all statements made on information and
14 belief are believed to be true; and further that these statements were
15 made with the knowledge that willful false statements and the like so
16 made are punishable by fine or imprisonment, or both, under
17 Section 1001 of Title 18 of the United States Code and that such willful
18 false statement may jeopardize the validity of the application or any
19 patent issued therefrom.
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Full name of sole inventor: **Pai-Hung Pan**

Inventor's Signature: Pai Hung Pan

Date: 08/26/96

Residence: **Boise, Idaho**

Citizenship: **U.S.A.**

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